1. Package summary

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Min</th>
<th>Typ</th>
<th>Nom</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>D</td>
<td>package length</td>
<td>1.15</td>
<td>-</td>
<td>1.2</td>
<td>1.25</td>
<td>mm</td>
</tr>
<tr>
<td>E</td>
<td>package width</td>
<td>0.75</td>
<td>-</td>
<td>0.8</td>
<td>0.85</td>
<td>mm</td>
</tr>
<tr>
<td>A</td>
<td>seated height</td>
<td>0.58</td>
<td>-</td>
<td>0.6</td>
<td>0.65</td>
<td>mm</td>
</tr>
<tr>
<td>n_2</td>
<td>actual quantity of termination</td>
<td>-</td>
<td>-</td>
<td>2</td>
<td>-</td>
<td></td>
</tr>
</tbody>
</table>
2. Package outline

Plastic surface-mounted package; 2 leads

SOD523

DIMENSIONS (mm are the original dimensions)

<table>
<thead>
<tr>
<th>UNIT</th>
<th>A</th>
<th>b_p</th>
<th>c</th>
<th>D</th>
<th>E</th>
<th>H_E</th>
<th>v</th>
</tr>
</thead>
<tbody>
<tr>
<td>mm</td>
<td>0.65</td>
<td>0.34</td>
<td>0.17</td>
<td>1.25</td>
<td>0.75</td>
<td>1.65</td>
<td>0.1</td>
</tr>
</tbody>
</table>

Note
1. The marking bar indicates the cathode.

Fig. 1. Package outline SOD523

3. Soldering

Fig. 2. Reflow soldering footprint for SOD523
4. Legal information

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